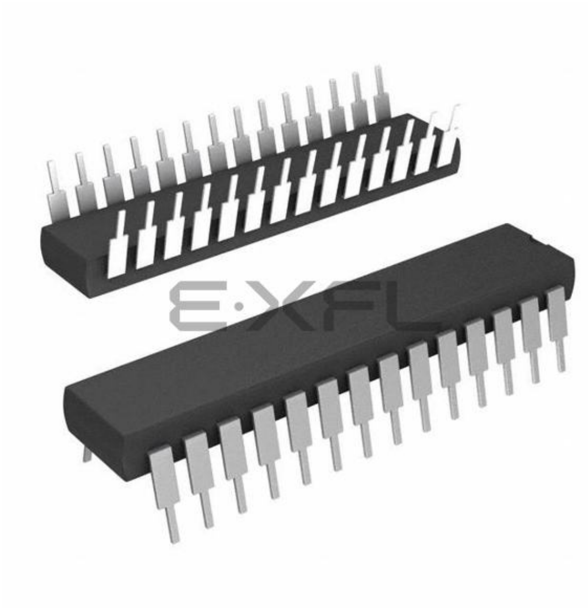


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp202-h-sp

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name[4]	Pin Type	Buffer Type	PPS	Description
AN0-AN15	I	Analog	No	Analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for Compare channels).
OCFB	I	ST	No	Compare Fault B input (for Compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
RA0-RA4, RA7-RA12	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC13, RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD5, RD6, RD8	I/O	ST	No	PORTD is a bidirectional I/O port.
RE12-RE15	I/O	ST	No	PORTE is a bidirectional I/O port.
RF0, RF1	I/O	ST	No	PORTF is a bidirectional I/O port.
RG6-RG9	I/O	ST	No	PORTG is a bidirectional I/O port.
T1CK	I	ST	No	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	No	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
CTPLS	O	ST	No	CTMU pulse output.
CTED1	I	ST	No	CTMU External Edge Input 1.
CTED2	I	ST	No	CTMU External Edge Input 2.
$\overline{\text{U1CTS}}$	I	ST	No	UART1 Clear-To-Send.
$\overline{\text{U1RTS}}$	O	—	No	UART1 Ready-To-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	No	UART1 IrDA® baud clock output.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

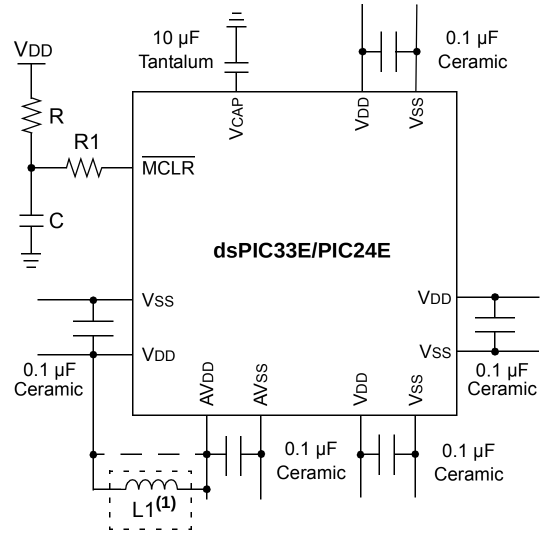
2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohm) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 30.0 “Electrical Characteristics”** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 27.3 “On-Chip Voltage Regulator”** for details.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions:

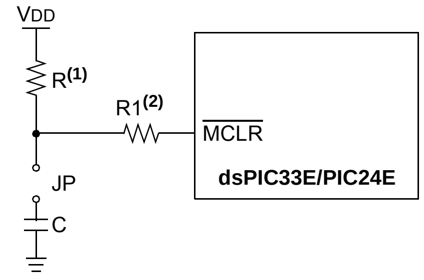
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-6).

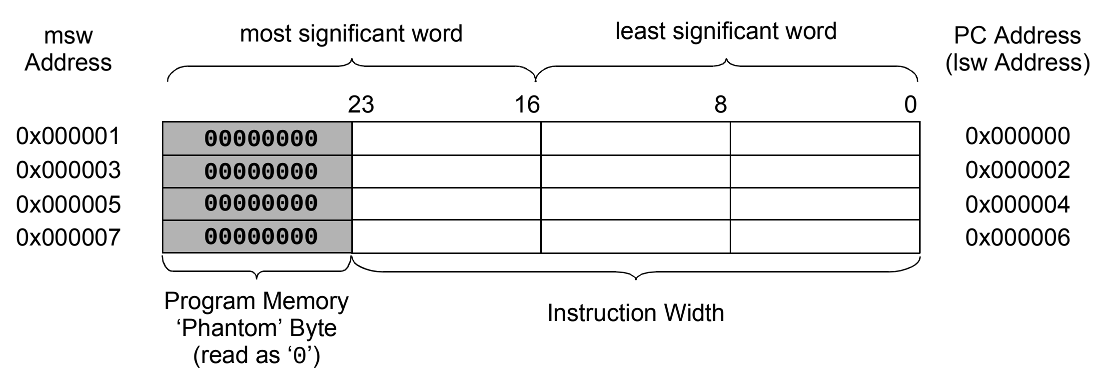
Program memory addresses are always word-aligned on the lower word and addresses are incremented, or decremented by two, during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A `GOTO` instruction is programmed by the user application at address, 0x000000, of Flash memory, with the actual address for the start of code at address, 0x000002, of Flash memory.

A more detailed discussion of the Interrupt Vector Tables (IVTs) is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-6: PROGRAM MEMORY ORGANIZATION



REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR(1)	OVBERR(1)	COVAERR(1)	COVBERR(1)	OVATE(1)	OVBTE(1)	COVTE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR(1)	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit(1)
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit(1)
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **DMACERR:** DMAC Trap Flag bit
1 = DMAC trap has occurred
0 = DMAC trap has not occurred

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PAD<15:0>:** Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER[1]

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CNT<13:8>[2]					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0>[2]							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-0 **CNT<13:0>:** DMA Transfer Count Register bits[2]

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

REGISTER 16-1: PTCON: PWMx TIME BASE CONTROL REGISTER (CONTINUED)

bit 6-4	**SYNCSRC<2:0>:** Synchronous Source Selection bits[(1)] `111` = Reserved • • • `100` = Reserved `011` = PTGO17[(2)] `010` = PTGO16[(2)] `001` = Reserved `000` = SYNCI1 input from PPS
bit 3-0	**SEVTPS<3:0>:** PWMx Special Event Trigger Output Postscaler Select bits[(1)] `1111` = 1:16 Postscaler generates Special Event Trigger on every sixteenth compare match event • • • `0001` = 1:2 Postscaler generates Special Event Trigger on every second compare match event `0000` = 1:1 Postscaler generates Special Event Trigger on every compare match event

Note 1: These bits should be changed only when PTEN = `0`. In addition, when using the SYNCI1 feature, the user application must program the period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

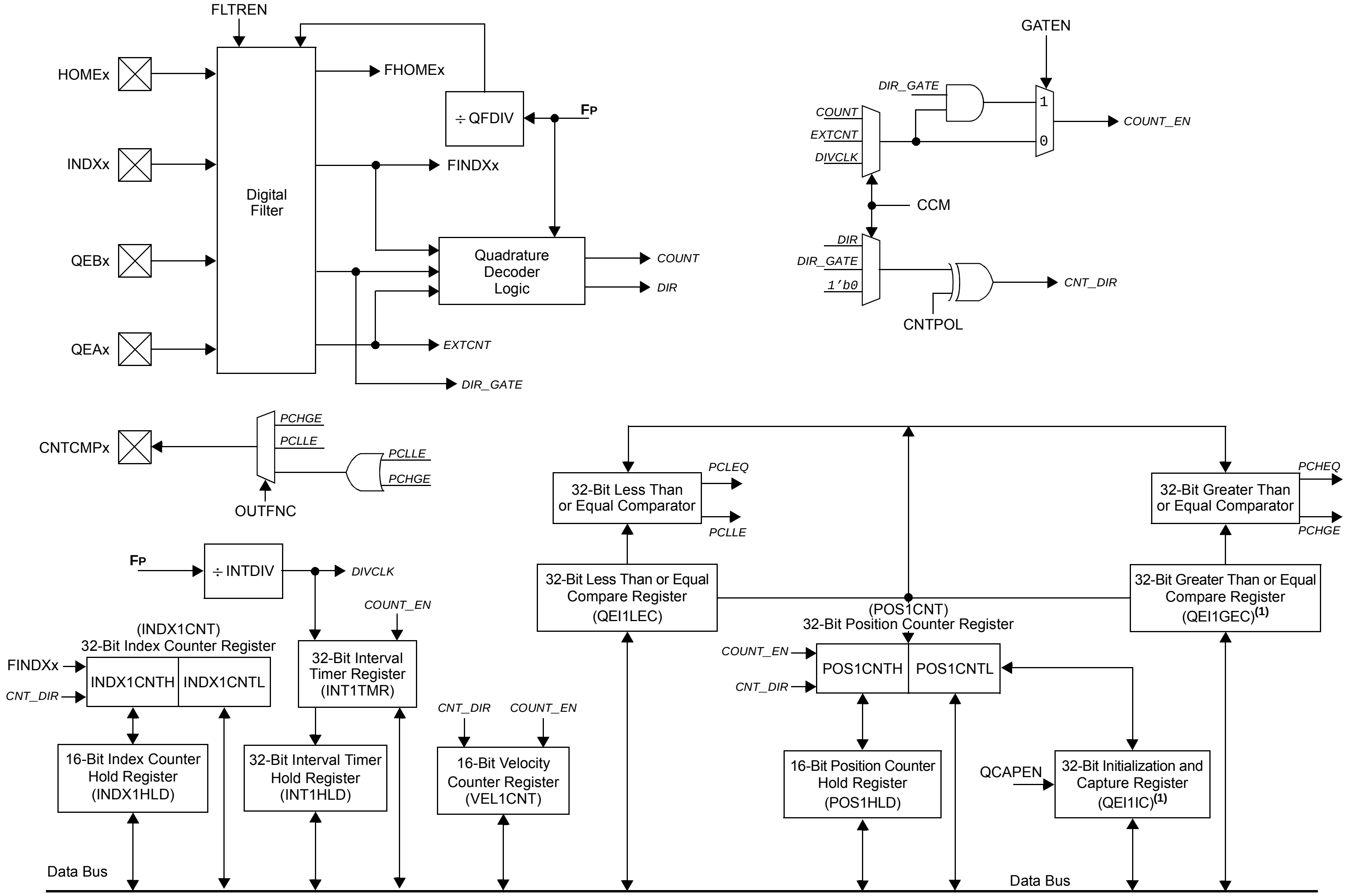
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**PHR:** PWMxH Rising Edge Trigger Enable bit 1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxH
bit 14	**PHF:** PWMxH Falling Edge Trigger Enable bit 1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxH
bit 13	**PLR:** PWMxL Rising Edge Trigger Enable bit 1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxL
bit 12	**PLF:** PWMxL Falling Edge Trigger Enable bit 1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxL
bit 11	**FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected Fault input 0 = Leading-Edge Blanking is not applied to selected Fault input
bit 10	**CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected current-limit input 0 = Leading-Edge Blanking is not applied to selected current-limit input
bit 9-6	**Unimplemented:** Read as ‘0’
bit 5	**BCH:** Blanking in Selected Blanking Signal High Enable bit(1) 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high 0 = No blanking when selected blanking signal is high
bit 4	**BCL:** Blanking in Selected Blanking Signal Low Enable bit(1) 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low 0 = No blanking when selected blanking signal is low
bit 3	**BPHH:** Blanking in PWMxH High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high 0 = No blanking when PWMxH output is high
bit 2	**BPHL:** Blanking in PWMxH Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low 0 = No blanking when PWMxH output is low
bit 1	**BPLH:** Blanking in PWMxL High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high 0 = No blanking when PWMxL output is high
bit 0	**BPLL:** Blanking in PWMxL Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low 0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

FIGURE 17-1: QEI BLOCK DIAGRAM



Note 1: These registers map to the same memory location.

18.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
    a) If FRMPOL (SPIxCON2<13>) = `1`, use a pull-down resistor on SSx.
    b) If FRMPOL = `0`, use a pull-up resistor on SSx.

> **Note:** This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using SSx from a master):
    a) If CKP (SPIxCON1<6>) = `1`, always place a pull-up resistor on SSx.
    b) If CKP = `0`, always place a pull-down resistor on SSx.

> **Note:** This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCKx transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = `1` and SSEN (SPIxCON1<7>) = `1` are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the SSx pin, which indicates the start of a data frame.

> **Note:** Not all third-party devices support Frame mode timing. Refer to the SPIx specifications in **Section 30.0 “Electrical Characteristics”** for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a ‘`1`’ for the fastest SPIx data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user’s master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.

18.2 SPI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

> **Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser:
> http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

18.2.1 KEY RESOURCES

- **“Serial Peripheral Interface (SPI)”** (DS70569) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

18.3 SPIx Control Registers

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>		
bit 15							bit 8

R/W-0	R/C-0, HS	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HS, HC	R-0, HS, HC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit

`1` = Enables the module and configures SCKx, SDOx, SDIx and $\overline{\text{SSx}}$ as serial port pins
`0` = Disables the module

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit

`1` = Discontinues the module operation when device enters Idle mode
`0` = Continues the module operation in Idle mode

bit 12-11 **Unimplemented:** Read as ‘`0`’

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)

Master mode:
Number of SPIx transfers that are pending.

Slave mode:
Number of SPIx transfers that are unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)

`1` = SPIx Shift register is empty and Ready-To-Send or receive the data
`0` = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit

`1` = A new byte/word is completely received and discarded; the user application has not read the previous data in the SPIxBUF register
`0` = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)

`1` = RX FIFO is empty
`0` = RX FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)

`111` = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
`110` = Interrupt when last bit is shifted into SPIxSR and as a result, the TX FIFO is empty
`101` = Interrupt when the last bit is shifted out of SPIxSR and the transmit is complete
`100` = Interrupt when one data is shifted into the SPIxSR and as a result, the TX FIFO has one open memory location
`011` = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
`010` = Interrupt when the SPIx receive buffer is 3/4 or more full
`001` = Interrupt when data is available in the receive buffer (SRMPT bit is set)
`000` = Interrupt when the last data in the receive buffer is read and as a result, the buffer is empty (SRXMPT bit is set)

REGISTER 21-10: CxCFG2: ECANx BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14	**WAKFIL:** Select CAN Bus Line Filter for Wake-up bit `1` = Uses CAN bus line filter for wake-up `0` = CAN bus line filter is not used for wake-up
bit 13-11	**Unimplemented:** Read as ‘`0`’
bit 10-8	**SEG2PH<2:0>:** Phase Segment 2 bits `111` = Length is 8 x TQ • • • `000` = Length is 1 x TQ
bit 7	**SEG2PHTS:** Phase Segment 2 Time Select bit `1` = Freely programmable `0` = Maximum of SEG1PHx bits or Information Processing Time (IPT), whichever is greater
bit 6	**SAM:** Sample of the CAN Bus Line bit `1` = Bus line is sampled three times at the sample point `0` = Bus line is sampled once at the sample point
bit 5-3	**SEG1PH<2:0>:** Phase Segment 1 bits `111` = Length is 8 x TQ • • • `000` = Length is 1 x TQ
bit 2-0	**PRSEG<2:0>:** Propagation Time Segment bits `111` = Length is 8 x TQ • • • `000` = Length is 1 x TQ

FIGURE 25-4: USER-PROGRAMMABLE BLANKING FUNCTION BLOCK DIAGRAM

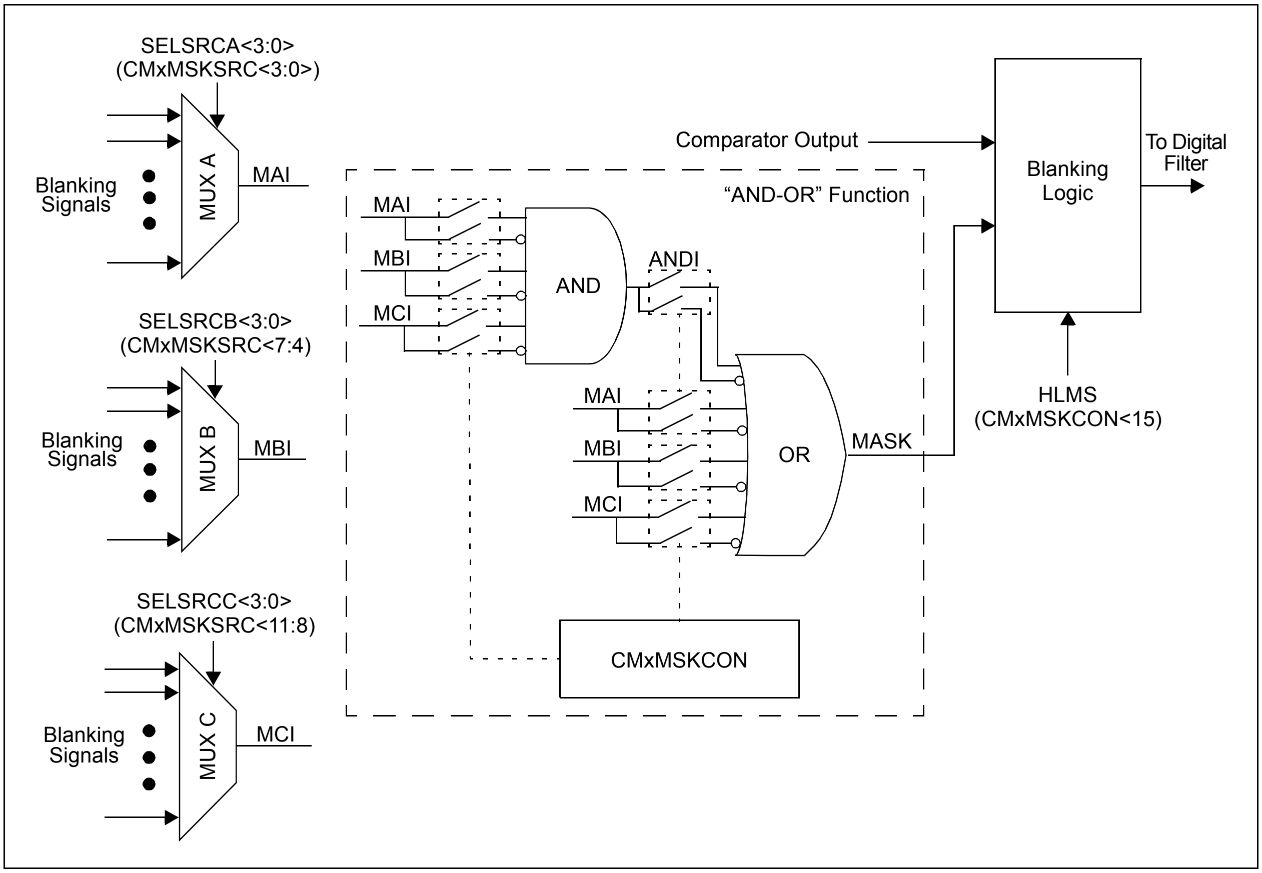
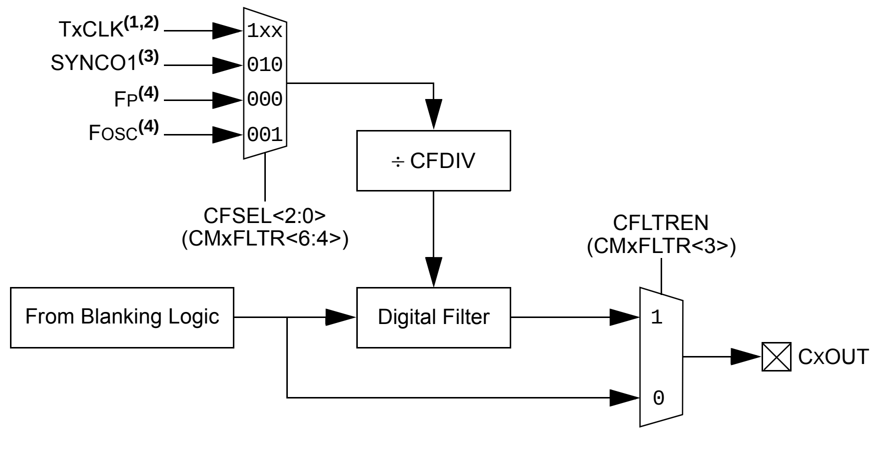


FIGURE 25-5: DIGITAL FILTER INTERCONNECT BLOCK DIAGRAM



Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

26.3 Programmable CRC Registers

REGISTER 26-1: CRCCON1: CRC CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R-0	R-0	R-0	R-0	R-0
CRCEN	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0
bit 15							bit 8

R-0	R-1	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CRCFUL	CRCMPT	CRCISEL	CRCGO	LENDIAN	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CRCEN:** CRC Enable bit
`1` = CRC module is enabled
`0` = CRC module is disabled; all state machines, pointers and CRCWDAT/CRCDAT are reset, other SFRs are not reset

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **CSIDL:** CRC Stop in Idle Mode bit
`1` = Discontinues module operation when device enters Idle mode
`0` = Continues module operation in Idle mode

bit 12-8 **VWORD<4:0>:** Pointer Value bits
Indicates the number of valid words in the FIFO. Has a maximum value of 8 when PLEN<4:0> > 7 or 16 when PLEN<4:0> ≤ 7.

bit 7 **CRCFUL**: CRC FIFO Full bit
`1` = FIFO is full
`0` = FIFO is not full

bit 6 **CRCMPT:** CRC FIFO Empty Bit
`1` = FIFO is empty
`0` = FIFO is not empty

bit 5 **CRCISEL:** CRC Interrupt Selection bit
`1` = Interrupt on FIFO is empty; final word of data is still shifting through CRC
`0` = Interrupt on shift is complete and CRCWDAT results are ready

bit 4 **CRCGO:** Start CRC bit
`1` = Starts CRC serial shifter
`0` = CRC serial shifter is turned off

bit 3 **LENDIAN:** Data Word Little-Endian Configuration bit
`1` = Data word is shifted into the CRC starting with the LSb (little endian)
`0` = Data word is shifted into the CRC starting with the MSb (big endian)

bit 2-0 **Unimplemented:** Read as ‘`0`’

TABLE 27-1: CONFIGURATION BYTE REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reserved	0057EC	32	—	—	—	—	—	—	—	—	—
	00AFEC	64									
	0157EC	128									
	02AFEC	256									
	0557EC	512									
Reserved	0057EE	32	—	—	—	—	—	—	—	—	—
	00AFEE	64									
	0157EE	128									
	02AFEE	256									
	0557EE	512									
FICD	0057F0	32	—	Reserved[3]	—	JTAGEN	Reserved[2]	Reserved[3]	—	ICS<1:0>	
	00AFF0	64									
	0157F0	128									
	02AFF0	256									
	0557F0	512									
FPOR	0057F2	32	—	WDTWIN<1:0>		ALTI2C2	ALTI2C1	Reserved[3]	—	—	—
	00AFF2	64									
	0157F2	128									
	02AFF2	256									
	0557F2	512									
FWDT	0057F4	32	—	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST<3:0>			
	00AFF4	64									
	0157F4	128									
	02AFF4	256									
	0557F4	512									
FOSC	0057F6	32	—	FCKSM<1:0>		IOL1WAY	—	—	OSCIOFNC	POSCMD<1:0>	
	00AFF6	64									
	0157F6	128									
	02AFF6	256									
	0557F6	512									
FOSCSEL	0057F8	32	—	IESO	PWMLOCK[1]	—	—	—	FNOSC<2:0>		
	00AFF8	64									
	0157F8	128									
	02AFF8	256									
	0557F8	512									
FGS	0057FA	32	—	—	—	—	—	—	—	GCP	GWRP
	00AFFA	64									
	0157FA	128									
	02AFFA	256									
	0557FA	512									
Reserved	0057FC	32	—	—	—	—	—	—	—	—	—
	00AFFC	64									
	0157FC	128									
	02AFFC	256									
	0557FC	512									
Reserved	057FFE	32	—	—	—	—	—	—	—	—	—
	00AFFE	64									
	0157FE	128									
	02AFFE	256									
	0557FE	512									

Legend: — = unimplemented, read as ‘1’.

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This bit is reserved and must be programmed as ‘0’.

3: These bits are reserved and must be programmed as ‘1’.

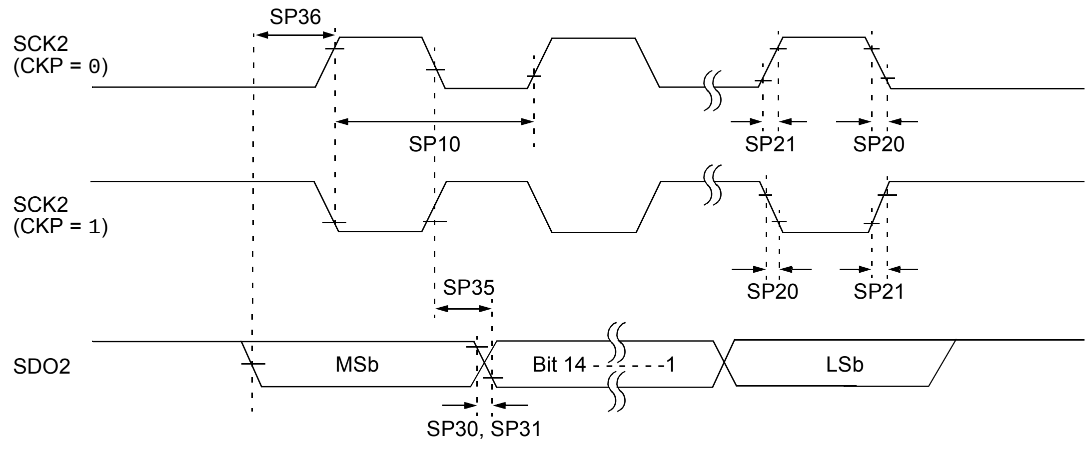
TABLE 30-22: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period	—	400	600	μs	
SY10	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY12	TWDT	Watchdog Timer Time-out Period	0.81	0.98	1.22	ms	WDTPRE = `0`, WDTPOST<3:0> = `0000`, using LPRC tolerances indicated in F21 (see Table 30-20) at +85ºC
			3.26	3.91	4.88	ms	WDTPRE = `1`, WDTPOST<3:0> = `0000`, using LPRC tolerances indicated in F21 (see Table 30-20) at +85ºC
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	0.68	0.72	1.2	μs	
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
SY30	TBOR	BOR Pulse Width (low)	1	—	—	μs	
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	μs	-40°C to +85°C
SY36	TVREG	Voltage Regulator Standby-to-Active mode Transition Time	—	—	30	μs	
SY37	TOSCDFRC	FRC Oscillator Start-up Delay	46	48	54	μs	
SY38	TOSCDLPRC	LPRC Oscillator Start-up Delay	—	—	70	μs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

FIGURE 30-15: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-34: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = `1`, CKP = `1`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic$^{(1)}$**	**Min.**	**Typ.$^{(2)}$**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of F_P or 11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 T_{CY} + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS2}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

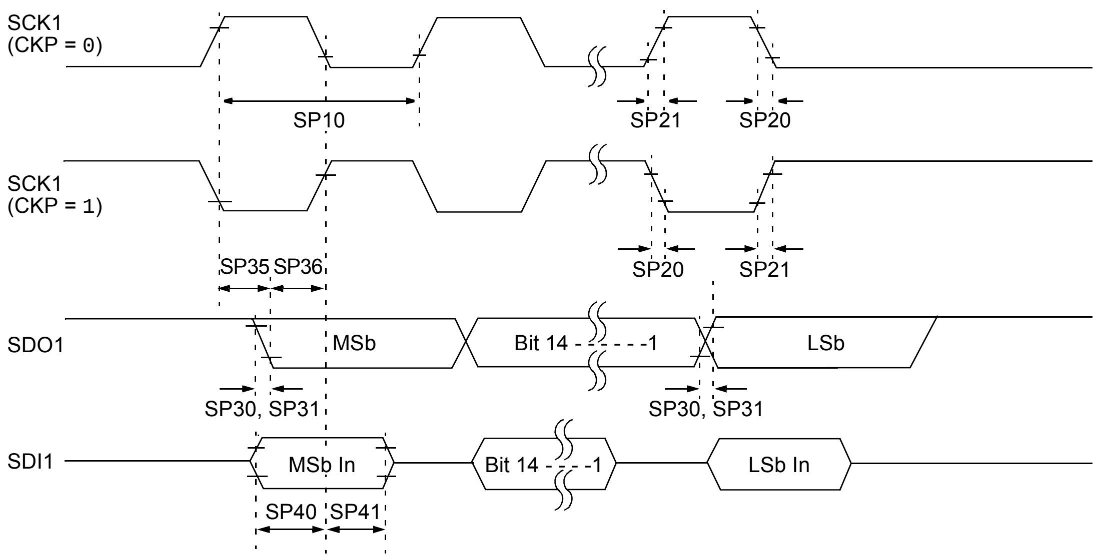
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-25: SPI1 MASTER MODE (FULL-DUPLEX, CKE = `0`, CKP = `x`, SMP = `1`) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-44: SPI1 MASTER MODE (FULL-DUPLEX, CKE = `0`, CKP = `x`, SMP = `1`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.